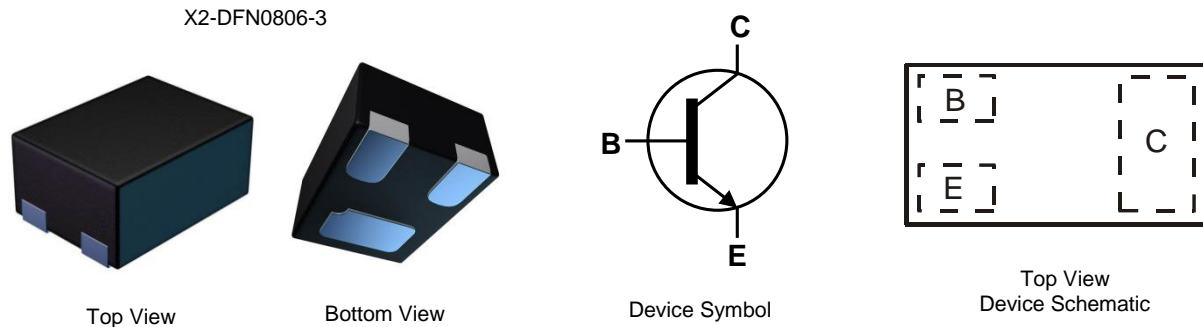


## Features

- $V_{CE0} > 45V$
- $I_C = 100mA$  High Collector Current
- $P_D = 435mW$  Power Dissipation
- $0.48mm^2$  Package Footprint, 16 times smaller than SOT23
- 0.4mm Height Package Minimizing Off-Board Profile
- Complementary PNP Type BC857BFA
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: X2-DFN0806-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu, Solderable per MIL-STD-202, Method 208
- Weight: 0.0008 grams (Approximate)

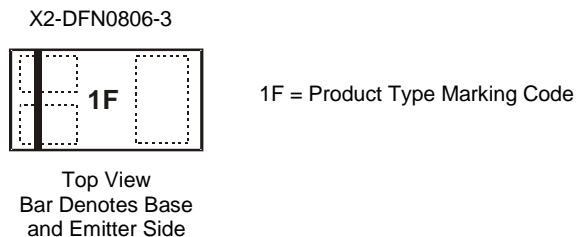


## Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC847BFA-7B	1F	7	8mm	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



## Absolute Maximum Ratings (@ $T_A = +25^\circ C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	50	V
Collector-Emitter Voltage	$V_{CEO}$	45	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Continuous Collector Current	$I_C$	100	mA
Peak Pulse Collector Current	$I_{CM}$	200	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

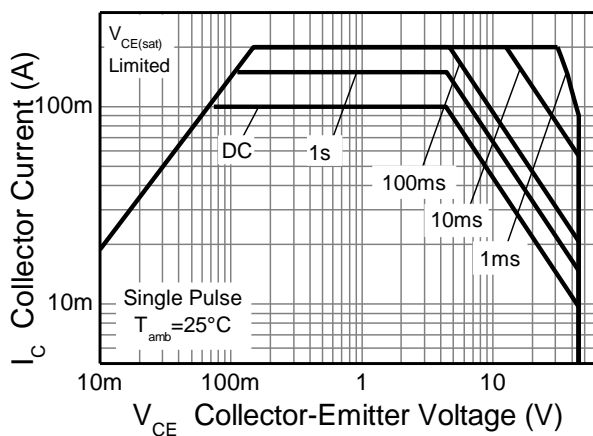
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	435	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	287	°C/W
Thermal Resistance, Junction to Lead (Note 6)	R <sub>θJL</sub>	150	°C/W
Operating and Storage and Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### ESD Ratings (Note 7)

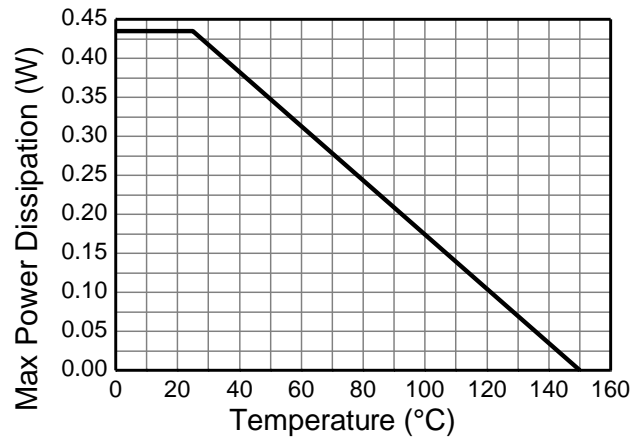
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	B

- Notes:
- For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
  - Thermal resistance from junction to solder-point (on the exposed collector pad).
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

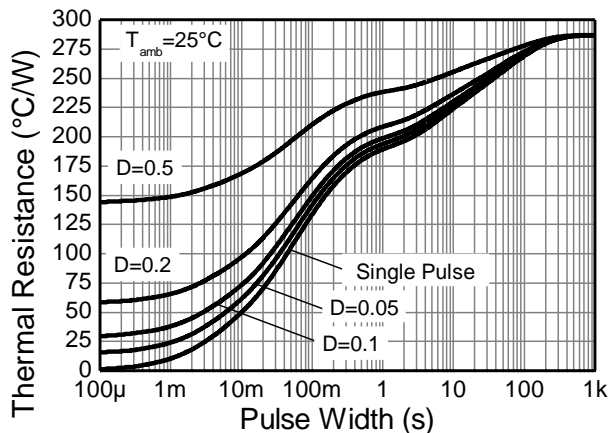
### Thermal Characteristics and Derating Information



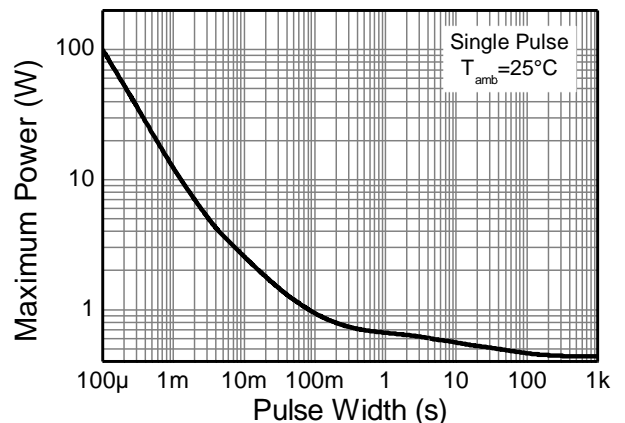
**Safe Operating Area**



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typical	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	50	150	—	V	I <sub>C</sub> = 50μA, I <sub>B</sub> = 0
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	50	150	—	—	I <sub>C</sub> = 50μA, I <sub>B</sub> = 0
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	45	65	—	V	I <sub>C</sub> = 1mA, I <sub>B</sub> = 0
Collector-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0	8.35	—	V	I <sub>E</sub> = 50μA, I <sub>C</sub> = 0
Collector-Base Cut-Off Current	I <sub>CBO</sub>	—	—	15	nA	V <sub>CB</sub> = 40V
Collector-Emitter Cut-Off Current	I <sub>CES</sub>	—	—	15	nA	V <sub>CE</sub> = 40V
<b>ON CHARACTERISTICS (Note 8)</b>						
DC Current Gain	h <sub>FE</sub>	— 200	220 260	— 470	—	I <sub>C</sub> = 10μA, V <sub>CE</sub> = 5.0V I <sub>C</sub> = 2.0mA, V <sub>CE</sub> = 5.0V
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	—	50 122	125 300	mV	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0.5mA I <sub>C</sub> = 100mA, I <sub>B</sub> = 5.0mA
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	—	760 880	1000 1100	mV	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0.5mA I <sub>C</sub> = 100mA, I <sub>B</sub> = 5.0mA
Base-Emitter Voltage	V <sub>BE(on)</sub>	580 —	650 725	750 800	mV	I <sub>C</sub> = 2.0mA, V <sub>CE</sub> = 5V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 5V
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Output Capacitance	C <sub>obo</sub>	—	1.5	—	pF	V <sub>CB</sub> = 10.0V, f = 1.0MHz, I <sub>E</sub> = 0
Current Gain-Bandwidth Product	f <sub>T</sub>	100	170	—	MHz	V <sub>CE</sub> = 5V, I <sub>C</sub> = 10mA, f = 100MHz

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

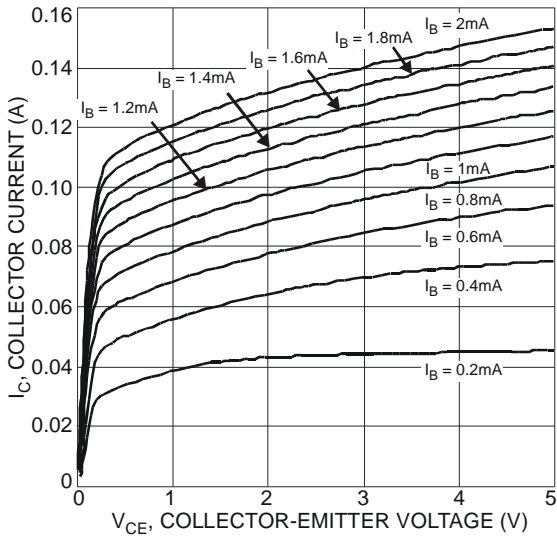


Fig. 4 Typical Collector Current vs. Collector-Emitter Voltage

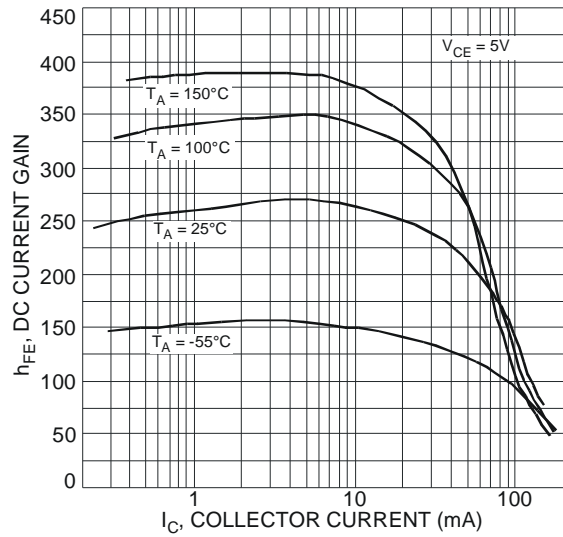


Fig. 5 Typical DC Current Gain vs. Collector Current

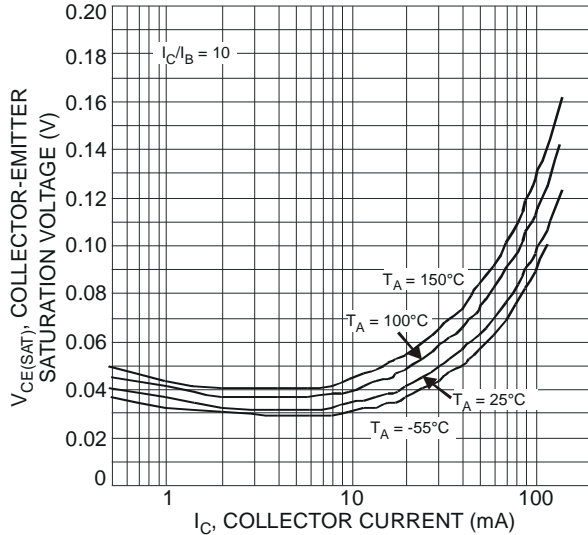


Fig. 6 Typical Collector-Emitter Saturation Voltage vs. Collector Current

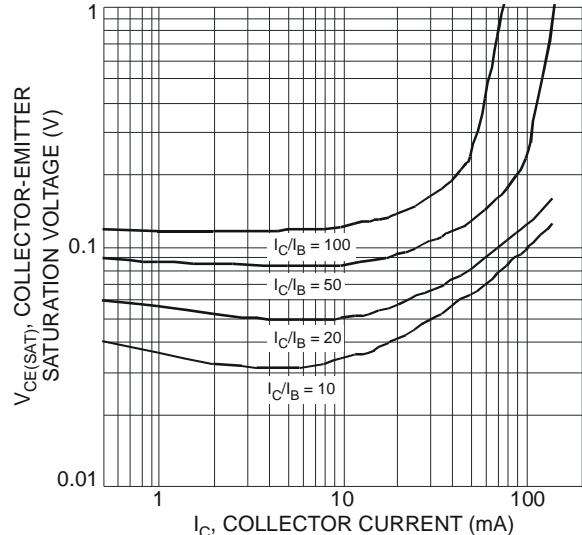


Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Collector Current

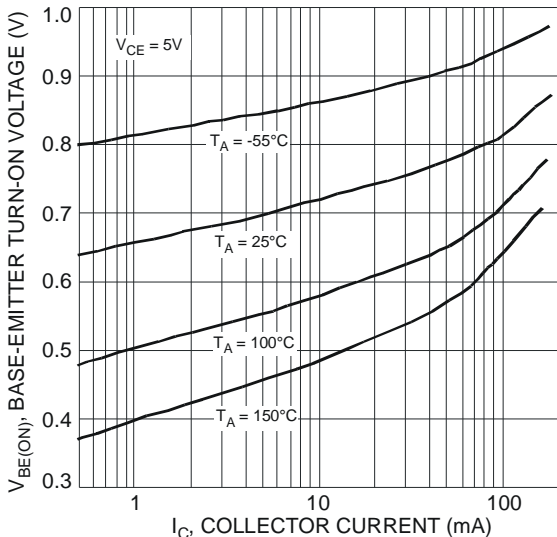


Fig. 8 Typical Base-Emitter Turn-On Voltage vs. Collector Current

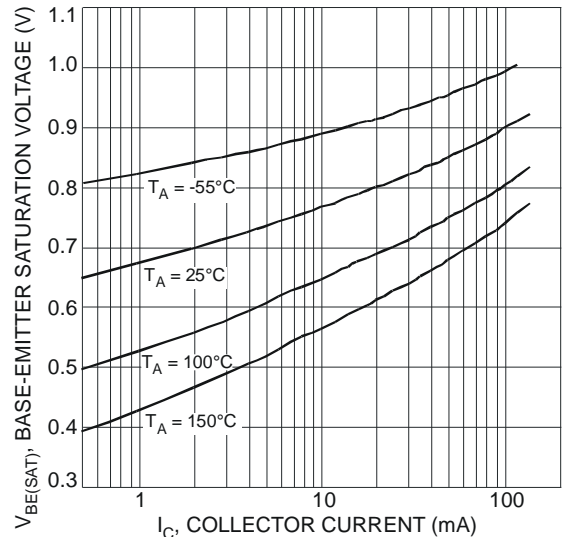
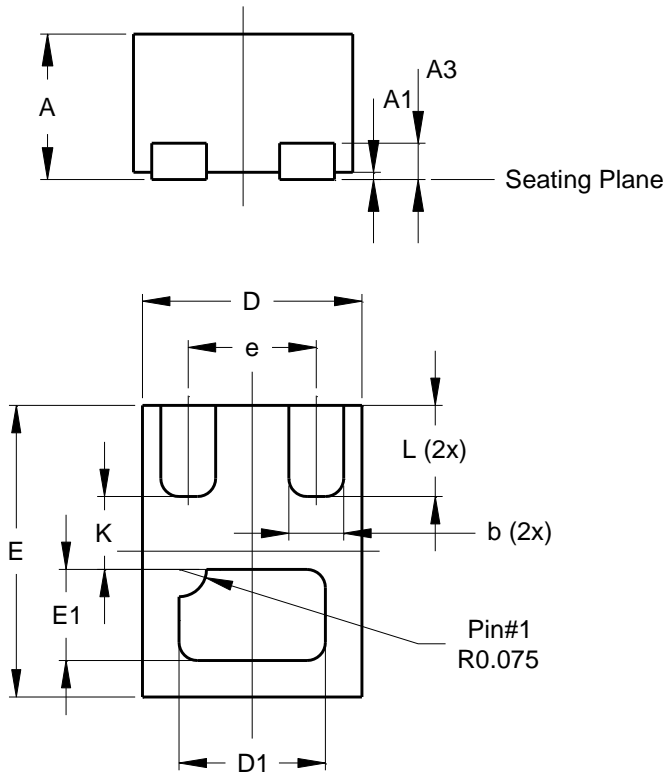


Fig. 9 Typical Base-Emitter Saturation Voltage vs. Collector Current

**Package Outline Dimensions**

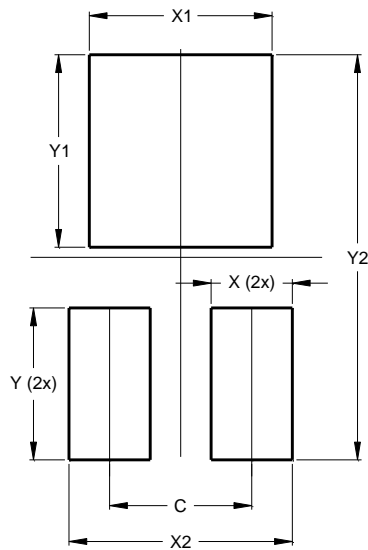
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN0806-3			
Dim	Min	Max	Typ
A	0.375	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.10
b	0.10	0.20	0.15
D	0.55	0.65	0.60
D1	0.35	0.45	0.40
E	0.75	0.85	0.80
E1	0.20	0.30	0.25
e	-	-	0.35
K	-	-	0.20
L	0.20	0.30	0.25
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.350
X	0.200
X1	0.450
X2	0.550
Y	0.375
Y1	0.475
Y2	1.000

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